Intel - EP4CE55U19I7N Datasheet





Welcome to <u>E-XFL.COM</u>

Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	3491
Number of Logic Elements/Cells	55856
Total RAM Bits	2396160
Number of I/O	324
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-FBGA
Supplier Device Package	484-UBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce55u19i7n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Manual Clock Switchover	5–30
Guidelines	5–30
Programmable Bandwidth	5–32
Phase Shift Implementation	5–32
PLL Cascading	5–33
PLL Reconfiguration	5–34
PLL Reconfiguration Hardware Implementation	5–34
Post-Scale Counters (C0 to C4)	5–36
Scan Chain Description	5–37
Charge Pump and Loop Filter	5–38
Bypassing a PLL Counter	5–39
Dynamic Phase Shifting	5–39
Spread-Spectrum Clocking	5–41
PLL Specifications	5–41
Document Revision History	5–42

Section II. I/O Interfaces

LNAPTER 6. I/U FEATURES IN LYCIONE IN DEVI
--

Cyclone IV I/O Elements	6–2
I/O Element Features	
Programmable Current Strength	6–3
Slew Rate Control	6–4
Open-Drain Output	
Bus Hold	6–4
Programmable Pull-Up Resistor	
Programmable Delay	
PCI-Clamp Diode	
OCT Support	
On-Chip Series Termination with Calibration	
On-Chip Series Termination Without Calibration	
I/O Standards	6–11
Termination Scheme for I/O Standards	
Voltage-Referenced I/O Standard Termination	6–14
Differential I/O Standard Termination	
I/O Banks	
High-Speed Differential Interfaces	
External Memory Interfacing	
Pad Placement and DC Guidelines	
Pad Placement	
DC Guidelines	
Clock Pins Functionality	
High-Speed I/O Interface	
High-Speed I/O Standards Support	
High Speed Serial Interface (HSSI) Input Reference Clock Support	
LVDS I/O Standard Support in Cyclone IV Devices	
Designing with LVDS	
BLVDS I/O Standard Support in Cyclone IV Devices	
Designing with BLVDS	
RSDS, Mini-LVDS, and PPDS I/O Standard Support in Cyclone IV Devices	
Designing with RSDS, Mini-LVDS, and PPDS	
LVPECL I/O Support in Cyclone IV Devices	
Differential SSTL I/O Standard Support in Cyclone IV Devices	

Power-Up Conditions and Memory Initialization

The M9K memory block outputs of Cyclone IV devices power up to zero (cleared) regardless of whether the output registers are used or bypassed. All M9K memory blocks support initialization using a **.mif**. You can create **.mif**s in the Quartus II software and specify their use using the RAM MegaWizard Plug-In Manager when instantiating memory in your design. Even if memory is pre-initialized (for example, using a **.mif**), it still powers up with its outputs cleared. Only the subsequent read after power up outputs the pre-initialized values.

To For more information about **.mif**s, refer to the *RAM Megafunction User Guide* and the *Quartus II Handbook*.

Power Management

The M9K memory block clock enables of Cyclone IV devices allow you to control clocking of each M9K memory block to reduce AC power consumption. Use the rden signal to ensure that read operations only occur when necessary. If your design does not require read-during-write, reduce power consumption by deasserting the rden signal during write operations or any period when there are no memory operations. The Quartus II software automatically powers down any unused M9K memory blocks to save static power.

Document Revision History

Table 3–6 shows the revision history for this chapter.

Table 3-6.	Document	Revision	History
------------	----------	----------	---------

Date	Version	Changes
November 2011	1.1	Updated the "Byte Enable Support" section.
November 2009	1.0	Initial release.

Table 4–2 lists the sign of the multiplication results for the various operand sign representations. The results of the multiplication are signed if any one of the operands is a signed value.

Da	ta A	Dat	Data B					
signa Value	Logic Level	signb Value	Logic Level	nesuit				
Unsigned	Low	Unsigned	Low	Unsigned				
Unsigned	Low	Signed	High	Signed				
Signed	High	Unsigned	Low	Signed				
Signed	High	Signed	High	Signed				

Table 4–2. Multiplier Sign Representation

Each embedded multiplier block has only one signa and one signb signal to control the sign representation of the input data to the block. If the embedded multiplier block has two 9 × 9 multipliers, the Data A input of both multipliers share the same signa signal, and the Data B input of both multipliers share the same signb signal. You can dynamically change the signa and signb signals to modify the sign representation of the input operands at run time. You can send the signa and signb signals through a dedicated input register. The multiplier offers full precision, regardless of the sign representation.

When the signa and signb signals are unused, the Quartus II software sets the multiplier to perform unsigned multiplication by default.

Output Registers

You can register the embedded multiplier output with output registers in either 18- or 36-bit sections, depending on the operational mode of the multiplier. The following control signals are available for each output register in the embedded multiplier:

- clock
- clock enable
- asynchronous clear

All input and output registers in a single embedded multiplier are fed by the same clock, clock enable, and asynchronous clear signals.

Operational Modes

You can use an embedded multiplier block in one of two operational modes, depending on the application needs:

- One 18 × 18 multiplier
- Up to two 9 × 9 independent multipliers

You can also use embedded multipliers of Cyclone IV devices to implement multiplier adder and multiplier accumulator functions, in which the multiplier portion of the function is implemented with embedded multipliers, and the adder or accumulator function is implemented in logic elements (LEs).

9-Bit Multipliers

You can configure each embedded multiplier to support two 9×9 independent multipliers for input widths of up to 9 bits.

Figure 4–4 shows the embedded multiplier configured to support two 9-bit multipliers.





All 9-bit multiplier inputs and results are independently sent through registers. The multiplier inputs can accept signed integers, unsigned integers, or a combination of both. Two 9 × 9 multipliers in the same embedded multiplier block share the same signa and signb signal. Therefore, all the Data A inputs feeding the same embedded multiplier must have the same sign representation. Similarly, all the Data B inputs feeding the same embedded multiplier must have the same sign representation.

GCLK Network Clock	GCLK Networks																			
Sources	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19
CLK15/DIFFCLK_6p (2)	—	—	_	—	—		—	—		—	—	_	_		_	~	_	_	~	—
PLL_1_C0 (3)	\checkmark	—		\checkmark	—	—	—	—	—	—	—	_	—	—	_	—	_	_	—	—
PLL_1_C1 (3)	—	\checkmark	—	—	\checkmark	—	—	—	—		—		—				_	_	_	—
PLL_1_C2 (3)	\checkmark	—	\checkmark	—	—	—	—	—	—	—	—	_	—	_	_	_			—	—
PLL_1_C3 (3)	—	~		~			_		_											—
PLL_1_C4 (3)	—	_	\checkmark	_	~	_	_	_	_		_								—	—
PLL_2_C0 (3)	—	—		—		~	—	—	~		—									—
PLL_2_C1 (3)	—	—	—	—	—	—	\checkmark	—	—	\checkmark	—		—	_			—	—	—	—
PLL_2_C2 (3)	—	_		_		\checkmark		~			_									—
PLL_2_C3 (3)	_	—	—	—	—	—	\checkmark	—	\checkmark	—	—	—	—	—	—	—	—	—	—	—
PLL_2_C4 (3)	—	—	—	—	—	—	—	\checkmark	—	\checkmark	—	—	—	—	—	—	—	—	—	—
PLL_3_C0	—	—	—	—	—	—	—	—	—	—	\checkmark	—	—	\checkmark	—	—	—	—	—	—
PLL_3_C1	—	—	—	—	—	—	—	—	—	—	—	\checkmark	—	_	\checkmark	—	—	—	—	—
PLL_3_C2	—	—	—	—	—	—	—	—	—	—	\checkmark	—	\checkmark	—	—	—	—	—	—	—
PLL_3_C3	—	—	—	—	—	—	—	—	—	—	—	\checkmark	—	\checkmark	—	—	—	—	—	—
PLL_3_C4	—	—	—	—	—	—	—	—	—	—	—	—	\checkmark	_	\checkmark	—	—	—	—	—
PLL_4_C0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	\checkmark	—	—	\checkmark	—
PLL_4_C1	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	\checkmark	—	—	\checkmark
PLL_4_C2	—	—		—	—	—	—	—	—		—		—	_		\checkmark	—	\checkmark	—	—
PLL_4_C3	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	\checkmark	—	\checkmark	—
PLL_4_C4	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	\checkmark	—	\checkmark
DPCLK0	\checkmark	—	—	—		—	—	—	—		—		—	—		—	—	—	—	—
DPCLK1	—	\checkmark	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
DPCLK7 (4)																				
CDPCLK0, Or	-	—	\checkmark	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
CDPCLK7 (2), (5)																				

 Table 5–3.
 GCLK Network Connections for Cyclone IV E Devices (1)
 (Part 2 of 3)

Figure 5–7 shows how to implement the clkena signal with a single register.

Figure 5–7. clkena Implementation



The clkena circuitry controlling the output C0 of the PLL to an output pin is implemented with two registers instead of a single register, as shown in Figure 5–7.

Figure 5–8 shows the waveform example for a clock output enable. The clkena signal is sampled on the falling edge of the clock (clkin).

This feature is useful for applications that require low power or sleep mode.

Figure 5–8. clkena Implementation: Output Enable



The clkena signal can also disable clock outputs if the system is not tolerant to frequency overshoot during PLL resynchronization.

Altera recommends using the clkena signals when switching the clock source to the PLLs or the GCLK. The recommended sequence is:

- 1. Disable the primary output clock by de-asserting the clkena signal.
- 2. Switch to the secondary clock using the dynamic select signals of the clock control block.
- 3. Allow some clock cycles of the secondary clock to pass before reasserting the clkena signal. The exact number of clock cycles you must wait before enabling the secondary clock is design-dependent. You can build custom logic to ensure glitch-free transition when switching between different clock sources.

Voltage-Referenced I/O Standard Termination

Voltage-referenced I/O standards require an input reference voltage (V_{REF}) and a termination voltage (V_{TT}). The reference voltage of the receiving device tracks the termination voltage of the transmitting device, as shown in Figure 6–5 and Figure 6–6.



Figure 6–5. Cyclone IV Devices HSTL I/O Standard Termination

Figure 6–6. Cyclone IV Devices SSTL I/O Standard Termination



The CLKIN/REFCLK pins are powered by dedicated V_{CC_CLKIN3A}, V_{CC_CLKIN3B}, V_{CC_CLKIN3B}, v_{CC_CLKIN8A}, and V_{CC_CLKIN8B} power supplies separately in their respective I/O banks to avoid the different power level requirements in the same bank for GPIO.

			VCC			I/O Pin Type			
I/O Standard	HSSI Protocol	Coupling	Termination	Input	Output	Column I/O	Row I/O	Supported I/O Banks	
LVDS	All		Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B	
LVPECL	All	Differential AC (Need	Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B	
	All	off chip resistor to	Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B	
1.2V, 1.5V, 3.3V PCML	All	restore V _{CM})	Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B	
All			Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B	
HCSL	PCIe	Differential DC	Off chip	2.5V	Not supported	Yes	No	3A, 3B, 8A, 8B	

Table 6–10. Cyclone IV GX HSSI REFCLK I/O Standard Support Using GPIO CLKIN Pins (1), (2)

Notes to Table 6-10:

(1) The EP4CGX15, EP4CGX22, and EP4CGX30 devices have two pairs of dedicated clock input pins in banks 3A and 8A for HSSI input reference clock. I/O banks 3B and 8B are not available in EP4CGX15, EP4CGX22, and EP4CGX30 devices.

(2) The EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices have four pairs of dedicated clock input pins in banks 3A, 3B, 8A, and 8B for HSSI input or single-ended clock input.

To For more information about the AC-coupled termination scheme for the HSSI reference clock, refer to the *Cyclone IV Transceivers Architecture* chapter.

LVDS I/O Standard Support in Cyclone IV Devices

The LVDS I/O standard is a high-speed, low-voltage swing, low power, and GPIO interface standard. Cyclone IV devices meet the ANSI/TIA/EIA-644 standard with the following exceptions:

- The maximum differential output voltage (V_{OD}) is increased to 600 mV. The maximum V_{OD} for ANSI specification is 450 mV.
- The input voltage range is reduced to the range of 1.0 V to 1.6 V, 0.5 V to 1.85 V, or 0 V to 1.8 V based on different frequency ranges. The ANSI/TIA/EIA-644 specification supports an input voltage range of 0 V to 2.4 V.
- For LVDS I/O standard electrical specifications in Cyclone IV devices, refer to the *Cyclone IV Device Datasheet* chapter.

Date	Version	Changes
		 Added Cyclone IV E devices information for the Quartus II software version 9.1 SP1 release.
February 2010 2.0	■ Updated Table 6–2, Table 6–3, and Table 6–10.	
	■ Updated "I/O Banks" section.	
	■ Added Figure 6–9.	
		■ Updated Figure 6–10 and Figure 6–11.
		■ Added Table 6–4, Table 6–6, and Table 6–8.
November 2009	1.0	Initial release.

 Table 6–12. Document Revision History (Part 2 of 2)

7. External Memory Interfaces in Cyclone IV Devices

This chapter describes the memory interface pin support and the external memory interface features of Cyclone[®] IV devices.

In addition to an abundant supply of on-chip memory, Cyclone IV devices can easily interface with a broad range of external memory devices, including DDR2 SDRAM, DDR SDRAM, and QDR II SRAM. External memory devices are an important system component of a wide range of image processing, storage, communications, and general embedded applications.

Altera recommends that you construct all DDR2 or DDR SDRAM external memory interfaces using the Altera[®] ALTMEMPHY megafunction. You can implement the controller function using the Altera DDR2 or DDR SDRAM memory controllers, third-party controllers, or a custom controller for unique application needs. Cyclone IV devices support QDR II interfaces electrically, but Altera does not supply controller or physical layer (PHY) megafunctions for QDR II interfaces.

This chapter includes the following sections:

- "Cyclone IV Devices Memory Interfaces Pin Support" on page 7–2
- "Cyclone IV Devices Memory Interfaces Features" on page 7–12
- For more information about supported maximum clock rate, device and pin planning, IP implementation, and device termination, refer to the *External Memory Interface Handbook*.

© 2016 Altera Corporation. All rights reserved. ALTERA, ARRIA, CYCLONE, HARDCOPY, MAX, MEGACORE, NIOS, QUARTUS and STRATIX words and logos are trademarks of Altera Corporation and registered in the U.S. Patent and Trademark Office and in other countries. All other words and logos identified as trademarks or service marks are the property of their respective holders as described at www.altera.com/common/legal.html. Altera warrants performance of its semiconductor products to current specifications in accordance with Altera's standard warranty, but reserves the right to make changes to any products and services at any time without notice. Altera assumes no responsibility or liability arising out of the application or use of any information, product, or service described herein except as expressly agreed to in writing by Altera. Altera customers are advised to obtain the latest version of device specifications before relying on any published information and before placing orders for products or services.



Architectural Overview

Figure 1–3 shows the Cyclone IV GX transceiver channel datapath.

Figure 1–3. Transceiver Channel Datapath for Cyclone IV GX Devices



Each transceiver channel consists of a transmitter and a receiver datapath. Each datapath is further structured into the following:

- Physical media attachment (PMA)—includes analog circuitry for I/O buffers, clock data recovery (CDR), serializer/deserializer (SERDES), and programmable pre-emphasis and equalization to optimize serial data channel performance.
- Physical coding sublayer (PCS)—includes hard logic implementation of digital functionality within the transceiver that is compliant with supported protocols.

Outbound parallel data from the FPGA fabric flows through the transmitter PCS and PMA, is transmitted as serial data. Received inbound serial data flows through the receiver PMA and PCS into the FPGA fabric. The transceiver supports the following interface widths:

- FPGA fabric-transceiver PCS—8, 10, 16, or 20 bits
- PMA-PCS—8 or 10 bits
- ***** The transceiver channel interfaces through the PIPE when configured for PCIe protocol implementation. The PIPE is compliant with version 2.00 of the *PHY Interface for the PCI Express Architecture* specification.

Chann	el Configuration	Quartus II Selection
Bonded	With rate match FIFO ⁽¹⁾	coreclkout clock feeds the FIFO read clock for the bonded channels. coreclkout clock is the common bonded low-speed clock, which also feeds the FIFO read clock and transmitter PCS in the bonded channels.
bonded	Without rate match FIFO	<code>rx_clkout</code> clock feeds the FIFO read clock. <code>rx_clkout</code> is forwarded through the receiver channel from low-speed recovered clock, which also feeds the FIFO write clock.

Table 1–13. Automatic RX Phase Compensation FIFO Read Clock Selection (Part 2 of 2)

Note to Table 1-13:

(1) Configuration with rate match FIFO is supported in transmitter and receiver operation.

When using user-specified clock option, ensure that the clock feeding rx_coreclk port has 0 ppm difference with the RX phase compensation FIFO write clock.

Calibration Block

This block calibrates the OCT resistors and the analog portions of the transceiver blocks to ensure that the functionality is independent of process, voltage, and temperature (PVT) variations.

Figure 1–40 shows the location of the calibration block and how it is connected to the transceiver blocks.

Figure 1–40. Transceiver Calibration Blocks Location and Connection



Note to Figure 1-40:

(1) Transceiver block GXBL1 is only available for devices in F484 and larger packages.

/																	`,
Functional Mode							Bas	sic (10-Bit	PMA-PCS	Interfac	ce Width)						
> [•••••								
Channel Bonding									×1, ×2, >	<4							
}																	·
Low-Latency PCS							Disable	d								Enal	bled
) - [,														
Word Aligner (Pattern Length)	Ν	Manual A (7-Bit,	lignment 10-Bit)			Bit (7-Bit,	Slip 10-Bit)]		A Sta	utomatic Syn ate Machine	chronizatio (7-Bit, 10-E	n Bit)			Disa	oled
· ·																	·
8B/10B Encoder/Decoder	Disabl	ed	Enal	bled	Disa	bled	Ena	abled	Disa	abled			Enabled	1		Disa	bled
) 								L		L		_			1		, ,
Rate Match FIFO	Disable	ed	Disa	bled	Disa	bled	Disa	abled	Disa	abled	D	isabled		Ena	bled	Disa	oled
·	<u> </u>		<u>1</u>					<u></u>		<u>+</u>			L			<u> </u>	
Byte SERDES	Disabled E	nabled	Disabled	Enabled	Disabled	Enabled	Disabled	Enabled	Disabled	Enable	ed Disabled	Ena	bled	Disabled	Enabled	Disabled	Enabled
}		[{
Data Rate (Gbps)	0.6-	0.6-	0.6-	0.6-	0.6-	0.6-	0.6-	0.6-	0.6-	0.6-	0.6-	0.	6-	0.6-	0.6-	0.6-	0.6-
	0.6-	0.6- 3.125	0.6-	0.6- 3.125	0.6-	0.6- 3.125	0.6-	0.6- 3.125	0.6-	0.6-	0.6-	0.	.6- 125	0.6-	0.6- 3.125	0.6-	0.6- 3.125
``````````````````````````````````````							•••••	····									{
Byte Ordering	Disabled Di	isabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disabled	Disable	ed Disabled	Disabled	Enabled	Disabled	Disabled	Disabled	Disabled
EPGA Eabria-to-				····	····				····	····	····						
Transceiver	10-Bit	20-Bit	8-Bit	16-Bit	10-Bit	20-Bit	8-Bit	16-Bit	10-Bit	20-Bit	t 8-Bit	16-Bit	16-Bit	8-Bit	16-Bit	∎ 10-Bit	20-Bit
FPGA Fabric-to-	60-	30-	60-	30-	60-	30-	60-	30-	60-	30-	60-	30-	30-	60-	30-	60-	30-
Transceiver Interface	125 60-	125 30-	125 60-	125 30-	125 60-	125 30-	125 60-	125 30-	125 60-	125 30-	125 60-	125 30-	125 30-	125 60-	125 30-	125 60-	125 30-
Fredquency (MHz)	156.25	156.25	156.25	156.25	156.25	156.25	156.25	156.25	156.25	156.2	5 156.25	156.25	156.25	156.25	156.25	156.25	156.25
				Applica F324 a	able for d and small	evices in er packa	ı Iges			Applic F484	cable for de and larger	vices in packages					
Parager						-											

### Figure 1-46. Transceiver Configurations in Basic Mode with a 10-Bit Wide PMA-to-PCS Interface

### **Rate Match FIFO Operation in Basic Mode**

In Basic mode, the rate match FIFO performs the following operations:

- Deletes a maximum of four skip patterns from a cluster, if there is one skip pattern left in the cluster after deletion
- Insert a maximum of four skip patterns in a cluster, if there are less than five skip patterns in the cluster after deletion
- Automatically deletes the data byte that causes the FIFO to go full and asserts the rx_rmfifofull flag synchronous to the subsequent data byte
- Automatically inserts /K30.7/ (9'h1FE) after the data byte that causes the FIFO to go empty and asserts the rx-fifoempty flag synchronous to the inserted /K30.7/ (9'h1FE)

### **Additional Options in Basic Mode**

In Basic mode, the transceiver supports the following additional options:

low-latency PCS operation

Cyclone IV GX transceivers do not have built-in support for some PCS functions such as auto-negotiation state machine, collision-detect, and carrier-sense. If required, you must implement these functions in a user logic or external circuits.

The 1000 Base-X PHY is defined by IEEE 802.3 standard as an intermediate or transition layer that interfaces various physical media with the media access control (MAC) in a GbE system. The 1000 Base-X PHY, which has a physical interface data rate of 1.25 Gbps consists of the PCS, PMA, and physical media dependent (PMD) layers. Figure 1–54 shows the 1000 Base-X PHY in LAN layers.



### Figure 1–54. 1000 Base-X PHY in a GbE OSI Reference Model

### Notes to Figure 1–54:

- (1) CSMA/CD = Carrier-Sense Multiple Access with Collision Detection
- (2) GMII = gigabit medium independent interface

Figure 1–56 shows the transceiver configuration in GIGE mode.



Figure 1–56. Transceiver Configuration in GIGE Mode

When configured in GIGE mode, three encoded comma (/K28.5/) code groups are transmitted automatically after deassertion of tx_digitalreset and before transmitting user data on the tx_datain port. This could affect the synchronization state machine behavior at the receiver.

Depending on when you start transmitting the synchronization sequence, there could be an even or odd number of encoded data (/Dx.y/) code groups transmitted between the last of the three automatically sent /K28.5/ code groups and the first /K28.5/ code group of the synchronization sequence. If there is an even number of /Dx.y/ code groups received between these two /K28.5/ code groups, the first /K28.5/ code group of the synchronization sequence begins at an odd code group boundary. An IEEE802.3-compliant GIGE synchronization state machine treats this as an error condition and goes into the Loss-of-Sync state. Figure 1–60 shows the transceiver channel datapath and clocking when configured in Serial RapidIO mode.





### Notes to Figure 1–60:

- (1) Optional rate match FIFO.
- (2) High-speed recovered clock.
- (3) Low-speed recovered clock.

## **Receive Bit-Slip Indication**

The number of bits slipped in the word aligner for synchronization in manual alignment mode is provided with the rx_bitslipboundaryselectout [4..0] signal. For example, if one bit is slipped in word aligner to achieve synchronization, the output on rx_bitslipboundaryselectout [4..0] signal shows a value of 1 (5'00001). The information from this signal helps in latency calculation through the receiver as the number of bits slipped in the word aligner varies at each synchronization.

## **Transmit Bit-Slip Control**

The transmitter datapath supports bit-slip control to delay the serial data transmission by a number of specified bits in PCS with tx_bitslipboundaryselect[4..0] port. With 8- or 10-bit channel width, the transmitter supports zero to nine bits of data slip. This feature helps to maintain a fixed round trip latency by compensating latency variation from word aligner when providing the appropriate values on tx_bitslipboundaryselect[4..0] port based on values on rx_bitslipboundaryselectout[4..0] signal.

## **PLL PFD feedback**

In Deterministic Latency mode, when transmitter input reference clock frequency is the same as the low-speed clock, the PLL that clocks the transceiver supports PFD feedback. When enabled, the PLL compensates for delay uncertainty in the low-speed clock (tx_clkout in ×1 configuration or coreclkout in ×4 configuration) path relative to input reference and the transmitter datapath latency is fixed relative to the transmitter input reference clock.

## **SDI Mode**

SDI mode provides the non-bonded (×1) transceiver channel datapath configuration for HD- and 3G-SDI protocol implementations.

Cyclone IV GX transceivers configured in SDI mode provides the serialization and deserialization functions that supports the SDI data rates as listed in Table 1–24.

SMPTE Standard ⁽¹⁾	Configuration	Data Rate (Mbps)	FPGA Fabric-to- Transceiver Width	Byte SERDES Usage	
		1/92 5	20-bit	Used	
292M	High definition (HD)	1405.5	10-bit	Not used	
		1/85	20-bit	Used	
		1405	10-bit	Not used	
424M	Third-generation (3C)	2967	20-bit	llead	
	minu-generation (50)	2970	20-011	USeu	

Table 1–24. Supported SDI Data Rates

#### Note to Table 1-24:

(1) Society of Motion Picture and Television Engineers (SMPTE).

SDI functions such as scrambling/de-scrambling, framing, and cyclic redundancy check (CRC) must be implemented in the user logic.

As shown in Figure 2–5, perform the following reset procedure for the receiver CDR in manual lock mode configuration:

- 1. After power up, assert pll areset for a minimum period of 1 µs (the time between markers 1 and 2).
- 2. Keep the tx digitalreset, rx analogreset, rx digitalreset, and rx locktorefclk signals asserted and the rx locktodata signal deasserted during this time period. After you deassert the pll areset signal, the multipurpose PLL starts locking to the input reference clock.
- 3. After the multipurpose PLL locks, as indicated by the pll locked signal going high (marker 3), deassert the tx digitalreset signal (marker 4). For the receiver operation, after deassertion of the busy signal, wait for two parallel clock cycles to deassert the rx_analogreset signal.
- 4. In a bonded channel group, wait for at least  $t_{LTR_LTD_Manual}$ , then deassert rx locktorefclk and assert rx locktodata (marker 7). At this point, the receiver CDR of all the channels enters into lock-to-data mode and starts locking to the received data.
- 5. After asserting the rx locktodata signal, wait for at least t_{LTD Manual} before deasserting rx_digitalreset (the time between markers 7 and 8). At this point, the transmitter and receiver are ready for data traffic.

## Non-Bonded Channel Configuration

In non-bonded channels, each channel in the ALTGX MegaWizard Plug-In Manager instance contains its own tx digitalreset, rx analogreset, rx digitalreset, and rx freqlocked signals.

You can reset each channel independently. For example, if there are four non-bonded channels, the ALTGX MegaWizard Plug-In Manager provides four each of the following signals: tx digitalreset, rx analogreset, rx digitalreset, and rx freqlocked.

Table 2-6 lists the reset and power-down sequences for one channel in a non-bonded configuration under the stated functional modes.

able 2–6. Reset and Power-Down Sequences for Non-Bonded Channel Configurations								
Channel Set Up	Receiver CDR Mode	Refer to						
Transmitter Only	Basic ×1	"Transmitter Only Channel" on page 2–11						
Receiver Only	Automatic lock mode	"Receiver Only Channel—Receiver CDR in Automatic Lock Mode" on page 2–11						
Receiver Only	Manual lock mode	"Receiver Only Channel—Receiver CDR in Manual Lock Mode" on page 2–12						
Receiver and Transmitter	Automatic lock mode	"Receiver and Transmitter Channel—Receiver CDR in Automatic Lock Mode" on page 2–13						
Receiver and Transmitter	Manual lock mode	"Receiver and Transmitter Channel—Receiver CDR in						

Follow the same reset sequence for all the other channels in the non-bonded configuration.

Manual Lock Mode" on page 2-14

- 4. Wait for at least t_{LTR_LTD_Manual} (the time between markers 6 and 7), then deassert the rx_locktorefclk signal. At the same time, assert the rx_locktodata signal (marker 7). At this point, the receiver CDR enters lock-to-data mode and the receiver CDR starts locking to the received data.
- 5. Deassert rx_digitalreset at least  $t_{LTD_Manual}$  (the time between markers 7 and 8) after asserting the rx_locktodata signal. At this point, the transmitter and receiver are ready for data traffic.

## **Reset Sequence in Loss of Link Conditions**

Loss of link can occur due to loss of local reference clock source or loss of the link due to an unplugged cable. Other adverse conditions like loss of power could also cause the loss of signal from the other device or link partner.

### Loss of Local REFCLK or Other Reference Clock Condition

Should local reference clock input become disabled or unstable, take the following steps:

- 1. Monitor pll_locked signal. Pll_locked is de-asserted if local reference clock source becomes unavailable.
- 2. Pll_locked assertion indicates a stable reference clock because TX PLL locks to the incoming clock. You can follow appropriate reset sequence provided in the device handbook, starting from pll_locked assertion.

### Loss of Link Due To Unplugged Cable or Far End Shut-off Condition

Use one or more of the following methods to identify whether link partner is alive:

- Signal detect is available in PCIe and Basic modes. You can monitor rx_signaldetect signal as loss of link indicator. rx_signaldetect is asserted when the link partner comes back up.
- You can implement a ppm detector in device core for modes that do not have signal detect to monitor the link. Ppm detector helps in identifying whether the link is alive.
- Data corruption or RX phase comp FIFO overflow or underflow condition in user logic may indicate a loss of link condition.

Apply the following reset sequences when loss of link is detected:

- For Automatic CDR lock mode:
  - a. Monitor rx_freqlocked signal. Loss of link causes rx_freqlocked to be deasserted when CDR moves back to lock-to-data (LTD) mode.
  - b. Assert rx_digitalreset.
  - c. rx_freqlocked toggles over time when CDR switches between lock-to-reference (LTR) and LTD modes.
  - d. If rx_freqlocked goes low at any point, re-assert rx_digitalreset.
  - e. If data corruption or RX phase comp FIFO overflow or underflow condition is observed in user logic, assert rx_digitalreset for 2 parallel clock cycles, then de-assert the signal.

## **IOE Programmable Delay**

Table 1–40 and Table 1–41 list the IOE programmable delay for Cyclone IV E 1.0 V core voltage devices.

Table 1–40. IOE Programmable Delay on Column Pins for Cyclone IV E 1.0 V Core Voltage Device
----------------------------------------------------------------------------------------------

		Number of Setting	Min Offset	Max Offset					
Parameter	Paths Affected			Fast (	Corner	Slow Corner			Unit
				C8L	18L	C8L	C9L	18L	
Input delay from pin to internal cells	Pad to I/O dataout to core	7	0	2.054	1.924	3.387	4.017	3.411	ns
Input delay from pin to input register	Pad to I/O input register	8	0	2.010	1.875	3.341	4.252	3.367	ns
Delay from output register to output pin	I/O output register to pad	2	0	0.641	0.631	1.111	1.377	1.124	ns
Input delay from dual-purpose clock pin to fan-out destinations	Pad to global clock network	12	0	0.971	0.931	1.684	2.298	1.684	ns

Notes to Table 1-40:

(1) The incremental values for the settings are generally linear. For the exact values for each setting, use the latest version of the Quartus II software.

(2) The minimum and maximum offset timing numbers are in reference to setting **0** as available in the Quartus II software.

Table 1–41.   IOE Programmable Delay on Row Pins for Cyclone IV E 1.0 V Core Voltage Device	s (1),	(2)
---------------------------------------------------------------------------------------------	--------	-----

		Numbor	Min Offset	Max Offset					
Parameter	Paths Affected	of Setting		Fast (	Corner	Slow Corner			Unit
				C8L	18L	C8L	C9L	18L	
Input delay from pin to internal cells	Pad to I/O dataout to core	7	0	2.057	1.921	3.389	4.146	3.412	ns
Input delay from pin to input register	Pad to I/O input register	8	0	2.059	1.919	3.420	4.374	3.441	ns
Delay from output register to output pin	I/O output register to pad	2	0	0.670	0.623	1.160	1.420	1.168	ns
Input delay from dual-purpose clock pin to fan-out destinations	Pad to global clock network	12	0	0.960	0.919	1.656	2.258	1.656	ns

Notes to Table 1-41:

(1) The incremental values for the settings are generally linear. For the exact values for each setting, use the latest version of the Quartus II software.

(2) The minimum and maximum offset timing numbers are in reference to setting **0** as available in the Quartus II software.